ANNOUNCEMENT

The Liu Huixian Earthquake Engineering Scholarship

The Huixian Earthquake Engineering Foundation (HXEEF), China and the US-China

Earthquake Engineering Foundation, USA, are pleased to announce the Liu Huixian

Earthquake Engineering Scholarship for graduate students in the field of earthquake

engineering from China, the United States and Singapore. Students who are selected for the

scholarship will receive a certificate and RMB 10,000.

Applicants for the 2010 program must submit their application to the Secretariat of HXEEF

by July 30, 2010, with a formal recommendation from the university or institute where they

are studying.

A panel of experts formed by both foundations will select the awardees. Scholarship winners

will be notified in October, 2010 and announced on the websites:

http://hxeef.iem.cn/ -- HXEEF,

http://www.iem.ac.cn/ -- Institute of Engineering Mechanics of China Earthquake

Administration (IEM, CEA).

Contact information:

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Attachment 1: The Evaluation Procedure of the Liu Huixian Earthquake Engineering

Scholarship in 2010

Attachment 2: Application Form for the Liu Huixian Earthquake Engineering Scholarship

The Liu Huixian Earthquake Engineering Scholarship

Evaluation Procedure in 2010

The Huixian Earthquake Engineering Foundation (HXEEF), China and the US-China Earthquake Engineering Foundation, USA, were established in 2002. Recently, the two foundations have agreed to establish the Liu Huixian Earthquake Engineering Scholarship to award talented students who are pursuing a master or doctor's degree in earthquake engineering or closely related fields. This document describes the evaluation procedure of the Scholarship.

Article 1 Recommending Organizations

Applicants must be nominated or recommended by universities or institutes that offer master or doctor degree programs in earthquake engineering or closely related fields located in China, the United States or Singapore. The recommendation may be made by the research supervisor of the applicants and the department head of the organization.

Article 2 Requirements of Applicants

Applicants for the Scholarship shall be:

- currently enrolled in a graduate program in earthquake engineering,
- less than 30 years of age as of Dec. 31, 2010,
- of excellent academic qualifications,
- having research project exposure.

Article 3 The Award

- 1. Awardees will receive a Certificate and RMB 10,000.
- 2. In 2010, eight (8) scholarships will be available. Each organization may recommend no more than 2 applicants.

Article 4 The Application Materials

- 1. The application form will be available in February, 2010 on the websites (http://hxeef.iem.cn/ and http://www.iem.ac.cn/)
- Application materials must be received by the Secretariat of HXEEF by July 30, 2010.
 Application materials include:
 - the application form
 - original transcripts
 - a letter of recommendation from research supervisor
 - copies of 5 referred journal publications
 - other evidence of research quality

All material should be submitted in triplicate plus an electronic version.

Article 5 Evaluation

- 1. The foundations will jointly appoint a panel of experts to evaluate the applications.
- 2. The awardees will be announced on the websites (http://hxeef.iem.cn/ and http://www.iem.ac.cn/) in October, 2010.
- 3. Awardees are required to submit a report after they have completed their intended_degrees.

Article 6 Responsibilities

The Foundations retain the right to conduct the evaluation process as they see fit.

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The Liu Huixian Earthquake Engineering Scholarship

| Application Form | | |
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| Recommending Organization: (University or Institute) | | |
| Department: | | |
| Name of Applicant: | | |
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| | | |
| Date: | | |

Application Form for the Liu Huixian Earthquake Engineering Scholarship

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| and Awards | First Author | | | | | | | |
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| | Scientific and Technological Awards and Patents | | | | | | | |

| Other Awards | | | | |
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| Jour Mor Year Coll Plac Con Tim Ach List of Achievement | rential Patterns: nal Paper: Author's Name. Title. Journal, Year, Volume No.: Page Number nograph: Author's Name. Book's Name. Edition. Place of Publication: Publisher, of Publication: Page Number ected Papers: Paper. Author's Name. Title. Compiler. Title of the Collected Papers, e of Publication: Publisher, Year of Publication: Page Number ference Paper: Author. Title. Title of the Conference. Place of the Conference. e of the Conference. Serial Number of the Paper/ Page Number evement Prize: People Who Accomplish the Achievement, the Awarding Project, Prize Name, Year of the Prize nt: People Who Accomplish the Patent, Name of the Patent, Category of the ent (invention/ pragmatic), Approved Year | | | |
| I hereby affirm that all information and materials given in this form are true and valid. Signature of the Applicant: Date: | | | | |

| Opinion of Supervisor | Signature : | Date: | |
|--|-------------|-------|--|
| Opinion of Recommending Organization | Signature: | Date: | |
| Opinion of the two Foundations | Signature : | Date: | |

Note:

*SCI: Science Citation Index **EI: Engineering Index

*** ISTP: Index to Scientific & Technical Proceedings